1 DECLARATION

EXPRESS

As the below-named inventor, I declare that:

My residence, post office address, and citizenship are as stated below under my name.

I believe I am the original, first, and sole inventor of the invention entitled "METHOD AND APPARATUS FOR PLANARIZING A MICROELECTRONIC SUBSTRATE WITH A TILTED PLANARIZING SURFACE," which is described and claimed in the specification and claims of Patent Application No. 09/388,828, which I filed in the United States Patent and Trademark Office on September 1, 1999 and for which a patent is sought.

I have reviewed and understand the contents of the above-identified specification and claims, as amended by any amendment specifically referred to herein (if any).

I acknowledge my duty to disclose information of which I am aware which is material to patentability and examination of this application in accordance with 37 C.F.R. § 1.56(a).

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.

Scott E. Moore

Date 12-21-94

Residence : City of City of Meridian, County of Ada

State of Idaho

Citizenship : United States of America

P.O. Address : 1840 E. Mary Lane

Meridian, Idaho 83642

SS MAIL NO.: EL673946799US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Scott E. Moore

Attorney Docket No.: 500199.04

Filed

: Concurrently herewith

Title

: METHOD AND APPARATUS FOR PLANARIZING A MICROELECTRONIC

SUBSTRATE WITH A TILTED PLANARIZING SURFACE

TRANSMITTAL FOR REVOCATION AND SUBSTITUTE POWER OF ATTORNEY

Box Patent Application Commissioner of Patents Washington, D.C. 20231

Sir:

Transmitted herewith and attached hereto as Addendum A is a true and correct copy of the Revocation and Substitute Power of Attorney executed June 1, 2000, in the aboveidentified application. The above-identified application is identified on Exhibit A.

Pursuant to 37 C.F.R. § 3.73, Michael L. Lynch, duly authorized designee of Assignee, has certified that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., recorded under Reel 010480 / Frame 0926, and certified that to the best of his knowledge and belief, title remains in the name of the Assignee.

Respectfully submitted,

DORSEY & WHITNEY LLP

Steven H. Arterberry

Registration No. 46,314

Enclosures:

Addendum A Exhibit A

1420 Fifth Avenue, Suite 3400 Seattle, Washington 98101-4010 (206) 903-8800 (telephone) (206) 903-8200 (fax)



Applicant: Scott E. Moore

Attorney Docket No.: 500199.01 (660073.791)

Serial No. : 08/388,828

Group Art Unit : 3723

Filed

: September 1, 1999

Examiner

: Unknown

Title

: METHOD AND APPARATUS FOR PLANARIZING A MICROELECTRONIC

SUBSTRATE WITH A TILTED PLANARIZING SURFACE

Assistant Commissioner for Patents Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventors.

Assignee hereby appoints EDWARD W. BULCHIS, Reg. No. 26,847; PAUL T. MEIKLEJOHN, Reg. No. 26,569; GLENN P. RICKARDS, Reg. No. 29,428; KIMTON N. ENG, Reg. No. 43,605; DALE C. BARR, Reg. No. 40,498; DAVID E. BOONE, Reg. No. 27,857; SCOTT W. DOYLE, Reg. No. 39,176; REED R. HEIMBECHER, Reg. No. 36,353; JOHN T. KENNEDY, Reg. No. 42,717; GREGORY D. LEIBOLD, Reg. No. 36,408; GARY M. POLUMBUS, Reg. No. 25,364; and THOMAS H. YOUNG, Reg. No. 25,796, comprising the firm of DORSEY & WHITNEY LLP, 1420 Fifth Avenue, Suite 3400, Seattle, Washington 98101; along with MICHAEL L. LYNCH, Reg. No. 30,871; LIA M. PAPPAS, Reg. No. 34,095; WALTER D. FIELDS, Reg. No. 37,130; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of Micron Technology, Inc., 8000 South Federal Way, Boise, Idaho 83706-9632, as its attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. Please direct all telephone calls to Edward W. Bulchis at (206) 903-8800 and telecopies to (206) 903-8820.



Edward W. Bulchis, Esq. Dorsey & Whitney LLP 1420 Fifth Avenue, Suite 3400 Seattle, Washington 98101 (206) 903-8800

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC. ASSIGNEE

Dec 21,1999

DATE

Michael L. Lynch

Chief Patent Counsel

Enclosure:

Copy of Assignment N:\users\bulchise\500199\elect

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re A	Application of:)
	Scott E. Moore) Docket No. 500199.01 (660073.791)
	Scott E. Moore) Disclosure No. 99-0167
Serial	No. 09/388,828)
) Group Art Unit 3723
Filed:	September 1, 1999)
)
For:	METHOD AND APPARATUS FOR)
	PLANARIZING A)
	MICROELECTRONIC SUBSTRATE)
	WITH A TILTED PLANARIZING)
	SURFACE)
)
		_

ASSIGNMENT:

X	Enclosed for recording
	Previously recorded
Date:	
Reel:	

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which was filed on , and assigned Application No. 09/388,828 and is entitled "METHOD AND APPARATUS FOR PLANARIZING A MICROELECTRONIC SUBSTRATE WITH A TILTED PLANARIZING SURFACE"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to



others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Scott E. Moore

STATE OF IDAHO

County of Mary

BEFORE ME, this Alst day of Menney, 1999, personally appeared the above-named individual, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that executed the same of own free will for the purpose therein expressed.

Notary or Consular Officer

My Commission Expires 3-26

Date: 12-21-99

ADDENDUM A

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Assistant Commissioner for Patents Washington, DC 20231

REVOCATION AND SUBSTITUTE POWER OF ATTORNEY

Sir:

In the matter of the patent application identified in Exhibit A attached hereto, I, MICHAEL L. LYNCH, declare that I am a duly authorized designee of Micron Technology, Inc. ("Micron"), the ASSIGNEE of the entire right, title and interest in and to the patent application identified in Exhibit A attached hereto. Documentary evidence of chain of title from the original owner to ASSIGNEE has been or is concurrently being filed with and recorded by the United States Patent Office. The evidentiary documents referred to in the instant Revocation and Power of Attorney have been reviewed by the undersigned, and it is certified that, to the best of ASSIGNEE's knowledge and belief, title is held solely in and by Micron.

On behalf ASSIGNEE, I revoke all power of attorney heretofore given, and hereby appoint EDWARD W. BULCHIS, Reg. No. 26,847; JON F. TUTTLE, Reg. No. 25,713; PAUL T. MEIKLEJOHN, Reg. No. 26,569; GLENN P. RICKARDS, Reg. No. 29,428; DALE C. BARR, Reg. No. 40,498; KIMTON N. ENG, Reg. No. 43,605; DAVID E. BOONE, Reg. No. 27,857; SCOTT W. DOYLE, Reg. No. 39,176; REED R. HEIMBECHER, Reg. No. 36,353; JOHN T. KENNEDY, Reg. No. 42,717; GREGORY D. LEIBOLD, Reg. No. 36,408; GARY M. POLUMBUS, Reg. No. 25,364; THOMAS H. YOUNG, Reg. No. 25,796; W. ROBINSON H. CLARK, Reg. No. 41,530; GREGORY J. GLOVER, Reg. No. 34,173; JOHN K. HARROP, Reg. No. 41,817; CHRIS McWHINNEY, Reg. No. 42,875; ALDO NOTO, Reg. No. 35,628; MATTHEW PHILLIPS, Reg. No. 43,403; JOHN W. RYAN, Reg. No. 33,771; AMI P. SHAH, Reg. No. 42,143; SEAN S. WOODEN,

CHAEL C. GILCHRIST, Reg. No. 9; BRIAN J. LAURENZO. Reg. No. 43,997: Reg. No. 34,207; SHANE COLEMAN, Reg. No. 44,623; RONALD J. BROWN, Reg. No. 29,016; DAVID E. BRUHN, Reg. No. 36,762; DAVID N. FRONEK, Reg. No. 25,678; JOSEPH F. HAAG, Reg. No. 42,612; STUART R. HEMPHILL, Reg. No. 28,084; GRANT A. JOHNSON, Reg. No. 42,696; KENNETH E. LEVITT, Reg. No. 39,747; NIALL A. MACLEOD, Reg. No. 41,963; SCOTT A. MARKS, Reg. No. 44,902; DEVAN V. PADMANABHAN, Reg. No. 38,262; GERALD H. SULLIVAN, Reg. No. 37,243; BRIAN PARK, Reg. No. 45,519; MARK W. ROBERTS, Reg No. 46,160; STEVEN H. ARTERBERRY, Reg. No. 46,314; PAUL F. RUSYN, Reg. No. 42,118; of the firm of DORSEY & WHITNEY LLP; along with MICHAEL L. LYNCH, Reg. No. 30,871; WALTER D. FIELDS, Reg. No. 37,130; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of MICRON TECHNOLOGY, INC., 8000 South Federal Way, Boise, Idaho 83706-9632, as its attorneys to transact all business in the Patent and Trademark Office connected therewith.

Please direct all future correspondence and telephone calls to:

Edward W. Bulchis, Esq. DORSEY and WHITNEY LLP U.S. Bank Centre, Suite 3400 1420 Fifth Avenue Seattle, Washington 98101 (206)903-8800 (206)903-8820 facsimile.

ASSIGNEE:

Micron Technology, Inc.

Date

By

Michael L. Lynch

Chief Patent Counsel

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Exhibit A

Appl. No.	Atty Dkt #	Applicants	<u>Filed</u>	<u>Title</u>
09/388,828	660073.791 (500199.01)	Scott E. Moore	01-Sep-99	Method and Apparatus for Planarizing a Microelectronic Substrate with a Tilted Planarizing Surface
Not yet assigned	500199.02 (660073.791D1)	Scott E. Moore	10-Aug-01	Method and Apparatus for Planarizing a Microelectronic Substrate with a Tilted Planarizing Surface
Not yet assigned	500199.03 (660073.791D2)	Scott E. Moore	14-Aug-01	Method and Apparatus for Planarizing a Microelectronic Substrate with a Tilted Planarizing Surface
Not yet assigned	500199.04 (660073.791D3)	Scott E. Moore	Concurrently Herewith	Method and Apparatus for Planarizing a Microelectronic Substrate with a Tilted Planarizing Surface

N:\users\dbarr\Micron Technology\Exhibit A